

**SEMICONDUCTOR PACKAGES AND METHODS FOR MAKING THE SAME****Abstract of the Invention**

Semiconductor package support elements including cover members  
5 attached to one or more reject die sites are provided. Methods for making the  
support elements of the present invention and for making semiconductor  
packages using the same are also provided. Reject die sites on defective  
substrates of a support element are covered prior to the encapsulation process  
using a cover member. The cover member comprises, for example, pressure-  
10 sensitive or temperature-activated tape, reject dies, or the like. The support  
elements and methods of the present invention virtually eliminate bleeding or  
flashing during encapsulation due to the presence of reject die sites. The  
support elements and methods of the present invention further ensure that  
functional dice are not sacrificed by being attached to reject die sites, thereby  
15 decreasing manufacturing costs while increasing yield of functional  
semiconductor packages.

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